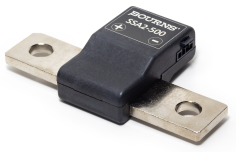
MATERIAL DECLARATION SHEET

Material number	SSA-250A-AE			
Product Line	Sensor & Controls			
Compliance Date	1/13/2026			
RoHS Compliant	Yes	MSL	N/A	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Capacitor 10 µF ±10%	Ceramic element	0.012	Barium Oxide	1304-28-5	60.00	0.012	0.019
				Titanium Dioxide	13463-67-7	30.00	0.006	
				Miscellaneous	Proprietary	10.00	0.0019	
		Outer Electrode	0.002	Copper	7440-50-8	90.00	0.003	0.003
				Boron Oxide	1303-86-2	2.00	0.00006	
				Silicon Dioxide	7631-86-9	8.00	0.0003	
		Plating Layer I	0.00008	Nickel	7440-02-0	100.00	0.0001	0.0001
		Inner Electrode	0.003	Nickel	7440-02-0	100.00	0.004	0.004
		Plating Layer II	0.0002	Tin	7440-31-5	100.00	0.0004	0.0004
2	Ceramic Capacitor 22 µF ±20% 3X	Ceramic Substrate	0.048	Barium Oxide	1304-28-5	60.00	0.047	0.078
				Titanium Dioxide	13463-67-7	30.00	0.023	
				Miscellaneous	Proprietary	10.00	0.008	
		Outer Electrode	0.009	Copper	7440-50-8	90.00	0.013	0.014
				Boron Oxide	1303-86-2	2.00	0.0003	
				Silicon Dioxide	7631-86-9	8.00	0.0011	
		Plating layer I	0.0003	Nickel	7440-02-0	100.00	0.0006	0.0006
		Inner Electrode	0.011	Nickel	7440-02-0	100.00	0.017	0.017
		Plating layer II	0.0009	Tin	7440-31-5	100.00	0.0015	0.002

3	Ceramic Capacitor 0.1 µF ±10% 3X	Ceramic Dielectric	0.044	Barium Titanium Trioxide	12047-27-7	99.04	0.070	0.071
				Miscellaneous	Proprietary	0.96	0.0007	
		Inner Electrode	0.004	Nickel	7440-02-0	100.00	0.007	0.007
		Termination	0.009	Copper	7440-50-8	72.95	0.010	0.014
				Miscellaneous	Proprietary	7.53	0.0011	
				Nickel	7440-02-0	4.79	0.0007	
				Tin	7440-31-5	14.73	0.002	
4	Diode 2X	Mold Compound	0.016	Fused Silica	60676-86-0	79.50	0.021	0.03
				Epoxy Resin	29690-82-2	10.00	0.003	
				Phenolic Resin	9003-35-4	10.00	0.003	
				Carbon Black	1333-86-4	0.50	0.0001	
		Lead Frame	0.005	Silicon	7440-21-3	36.30	0.003	0.008
				Manganese	7439-96-5	50.20	0.004	
				Nickel	7440-02-0	13.50	0.0010	
				Cobalt	7440-48-4	3.00	0.0002	
				Iron	7439-89-6	0.50	0.00004	
				Phosphorus	7723-14-0	3.00	0.0002	
				Carbon	7440-44-0	80.00	0.006	
				Carbon Black	1333-86-4	1.00	0.00008	
				Sulfur	7704-34-9	8.00	0.0006	
				Chromium	7440-47-3	4.50	0.0003	
		Plating 1	0.000005	Copper	7440-50-8	100.00	0.000007	0.000007
		Plating 2	0.000001	Silver	7440-22-4	100.00	0.000002	0.000002
		Terminal	0.0003	Tin	7440-31-5	100.00	0.0005	0.0005
		Chip	0.0001	Silicon	7440-21-3	99.57	0.0002	0.0002
				Silicon Dioxide	14808-60-7	0.43	0.0000010	
		Chip Metal	0.00001	Gold	7440-57-5	100.00	0.00002	0.00002
		Bond Wire	0.00002	Copper	7440-50-8	100.00	0.00003	0.00003
		Bond Wire Plating 1	0.0000004	Palladium	7440-05-3	100.00	0.0000006	0.0000006

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		Bond Wire Plating 1	0.0000004	Gold	7440-57-5	100.00	0.0000006	0.0000006
5	Connector	LCP-GF30	0.34	Carbon Black	1333-86-4	0.50	0.003	0.551
				Liquid Crystal Polymer	70679-92-4	68.00	0.375	
				Further Additives	Proprietary	1.50	0.008	
				Glass Fiber	65997-17-3	30.00	0.165	
		Tin Plating	0.003	Tin	7440-31-5	100.00	0.006	0.006
		Gold Plating	0.0004	Cobalt	7440-48-4	99.50	0.0007	0.0007
				Nickel	7440-02-0	0.25	0.000002	
				Gold	7440-57-5	0.25	0.000002	
		Nickel Plating	0.006	Nickel	7440-02-0	100.00	0.010	0.010
		Cartridge Brass 70% Unplate	0.172	Copper	7440-50-8	70.00	0.195	0.279
				Nickel	7440-02-0	30.00	0.084	
6	Fixed Inductor	Ferrite	0.013	Nickel Zinc Iron Oxide Nanopowder 99+%	1309-37-1	100.00	0.021	0.02
		Inner Electrode	0.0005	Silver	7440-22-4	100.00	0.001	0.001
		Terminal Electrode Plating	0.0003	Silver	7440-22-4	100.00	0.0005	0.0005
		Terminal Electrode	0.002	Silver	7440-22-4	88.00	0.002	0.0028
				Silicon Dioxide	60676-86-0	4.00	0.0001	
				Other	Proprietary	8.00	0.0002	
		Electro Plating I	0.0001	Copper	7440-50-8	100.00	0.0002	0.0002
		Electro Plating II	0.00008	Nickel	7440-02-0	100.00	0.0001	0.0001
		Electro Plating III	0.0002	Tin	7440-31-5	100.00	0.0004	0.0004
7	Converters / Transformer	Header	0.488	diallyl phthalate resin	25035-78-3	25.00	0.198	0.790
				Aluminum hydroxide.	21645-51-2	40.00	0.316	
				Antimony oxide(Sb2O3)	1309-64-4	4.50	0.036	
				Glass fiber	65997-17-3	30.00	0.237	
				Carbon black	1333-86-4	0.50	0.004	
		Terminal	0.064	Copper	7440-50-8	93.08	0.097	0.104

				Tin	7440-31-5	6.00	0.006	
				Phosphorus	7723-14-0	0.25	0.0003	
				Nickel	7440-02-0	0.20	0.0002	
				Zinc	7440-66-6	0.30	0.0003	
				Iron	7439-89-6	0.10	0.00010	
				Lead	7439-92-1	0.02	0.00002	
				Trade secret	Proprietary	0.05	0.00005	
		Ceramic	0.122	Iron oxide	1317-61-9	70.00	0.138	0.197
				Manganese oxide	1317-35-7	17.00	0.034	
				Zinc oxide	1314-13-2	13.00	0.026	
		Solder	0.035	Silver	7440-22-4	4.00	0.002	0.057
				Tin	7440-31-5	96.00	0.054	
		Coating	0.001	Paracyclophane	1633-22-3	99.00	0.002	0.002
				Trade Secret	Proprietary	1.00	0.00002	
		Adhesives, sealants	0.020	Bisphenol A diglycidyl ether resin	25068-38-6	55.00	0.018	0.032
				Talc	14807-96-6	7.50	0.002	
				Crystalline silica	14808-60-7	1.00	0.0003	
				Titanium oxide	13463-67-7	0.50	0.0002	
				Limestone	1317-65-3	29.00	0.009	
				Additives	Trade Secret	7.00	0.002	
		Pin Plating I	0.001	Nickel	7440-02-0	99.90	0.002	0.002
				Trade secret	Proprietary	0.10	0.000002	
		Pin Plating II	0.002	Tin	7440-31-5	99.90	0.004	0.004
				Trade secret	Proprietary	0.10	0.000	
		Wire I	0.030	Copper	7440-50-8	100.00	0.048	0.048
		Wire Plating I	0.0006	Tin	7440-31-5	100.00	0.0010	0.0010
		Wire Insulation	0.020	Propane, 1,1,1,2,2,3,3-Heptafluoro-3-[(Trifluoroethenyl)Oxy]-, Polymer With Tetrafluoroethene	26655-00-5	99.50	0.032	0.032

				Trade secret	Proprietary	0.50	0.0002	
		Wire II	0.046	Copper	7440-50-8	100.00	0.075	0.075
		Wire II Coating	0.005	Polyurethane	9009-54-5	97.23	0.008	0.008
				Polyamide	63428-84-2	2.77	0.0002	
8	IC	Bond Wire	0.0003	Iron	7439-89-6	0.0003	0.000000002	0.0005
				Calcium	7440-70-2	0.0003	0.000000002	
				Yttriu	7440-65-5	0.00066	0.000000003	
				Gold	7440-57-5	99.998	0.00048	
				Silver	7440-22-4	0.00099	0.000000005	
		Die Attach Adhesive	0.0005	Silver	7440-22-4	75.00	0.0007	0.0009
				Epoxy	85954-11-6	25.00	0.0002	
		Die Attach Adhesive 2	0.0005	Silver	7440-22-4	75.00	0.0006	0.0008
				Epoxy	85954-11-6	25.00	0.0002	
		Die Attach Adhesive 3	0.0002	Silver	7440-22-4	75.00	0.0002	0.0003
				Epoxy	85954-11-6	25.00	0.00008	
		Die Attach Adhesive 4	0.0002	Silver	7440-22-4	75.00	0.0002	0.0003
				Epoxy	85954-11-6	25.00	0.00008	
		Lead Frame	0.199	Copper	7440-50-8	97.05	0.312	0.32
				Iron	7439-89-6	2.60	0.008	
				Phosphorus	7723-14-0	0.15	0.0005	
				Zinc	7440-66-6	0.20	0.0006	
		Lead Frame Plating	0.0007	Nickel	7440-02-0	95.12	0.0011	0.001
				Gold	7440-57-5	0.78	0.000009	
				Palladium	7440-05-3	4.10	0.00005	
		Mold Compound	0.207	Silica Glass	60676-86-0	89.50	0.300	0.335
				Carbon Black	1333-86-4	0.50	0.0017	
				Chlorine	7782-50-5	0.002	0.000007	
				4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6	10.00	0.034	
		Semiconductor	0.002	Silicon	7440-21-3	100.00	0.003	0.003

		Semiconductor 2	0.002	Silicon	7440-21-3	100.00	0.003	0.003
		Semiconductor 3	0.001	Silicon	7440-21-3	100.00	0.0012	0.001
		Semiconductor 4	0.001	Silicon	7440-21-3	100.00	0.0012	0.001
9	IC	Bond Wire	0.00009	Gold	7440-57-5	100.00	0.0001	0.00014
		Die Attach Adhesive	0.0002	Silver	7440-22-4	80.00	0.0002	0.0003
				4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6	20.00	0.00005	
		Lead Frame	0.006	Copper	7440-50-8	97.44	0.009	0.009
				Iron	7439-89-6	2.35	0.0002	
				Phosphorus	7723-14-0	0.08	0.000008	
				Zinc	7440-66-6	0.13	0.000012	
		Lead Frame Plating	0.0000004	Nickel	7440-02-0	95.24	0.0000006	0.0000006
				Gold	7440-57-5	0.75	0.000000005	
				Palladium	7440-05-3	4.01	0.00000003	
		Mold Compound	0.009	Silicon Dioxide	60676-86-0	86.00	0.012	0.014
				Carbon Black	1333-86-4	0.50	0.00007	
				4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6	13.50	0.0019	
		Semiconductor	0.0005	Silicon	7440-21-3	100.00	0.0008	0.0008
10	IC	Bond Wire	0.00002	Gold	7440-57-5	100.00	0.00003	0.00003
		Die Attach Adhesive	0.0002	Silver	7440-22-4	75.00	0.0003	0.0004
				Epoxy	85954-11-6	52.00	0.0002	
		Lead Frame	0.005	Copper	7440-50-8	99.28	0.0088	0.009
				Chromium	7440-47-3	0.25	0.00002	
				Tin	7440-31-5	0.25	0.00002	
				Zinc	7440-66-6	0.22	0.00002	

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		Lead Frame Plating	0.0002	Nickel	7440-02-0	95.12	0.0003	0.0003
				Gold	7440-57-5	0.78	0.000002	
				Palladium	7440-05-3	4.10	0.000013	
		Mold Compound	0.011	Silicon	60676-86-0	85.00	0.016	0.018
				Carbon Black	1333-86-4	0.30	0.00005	
				4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6	14.70	0.003	
		Semiconductor	0.0009	Silicon	7440-21-3	100.00	0.0014	0.0014
11	PCB	Laminate	4.613	Electronic Grade Woven Glass cloth	65997-17-3	31.00	2.316	7.472
				Copper Foil	7440-50-8	40.00	2.989	
				Bromine -base epoxy resin	26265-08-7	18.00	1.345	
				Brominated Epoxy Flame retardants	68928-70-1	5.00	0.374	
				SiO2 Silicon Dioxide	14808-60-7	6.00	0.448	
		Solder Mask	0.010	Formaldehyde polymer with (chloromethyl)oxirane and methylphenol, 4-cyclohexene-1,2-dicarboxylate 2-propenoate	182697-62-7	56.800	0.009	0.016
				Barium Sulfate	7727-43-7	29.800	0.005	
				Silicon Dioxide	14808-60-7	1.400	0.0002	
				Bentonite	1302-78-9	1.400	0.0002	
				(29H,31H-phthalocyaninato(2-)-N29,N30,N31,N32)copper	147-14-8	1.400	0.0002	
				Pigment yellow	5102-83-0	0.700	0.0001	
				Silicone oil	63148-62-9	1.400	0.0002	
				Dipentaerythritol Hexaacrylate	29570-58-9	7.100	0.001	
		Metal	0.245	Copper	7440-50-8	99.98	0.397	0.397
				Phosphorus	7723-14-0	0.03	0.000	
		Legend	0.001	Ebecryl 600	71281-65-7	20.00	0.0003	0.002
				Titanium Oxide	1317-80-2	20.00	0.0003	
				Hexamethylene diacrylate	13048-33-4	30.00	0.0005	

				Trimethylolpropane triacrylate	15625-89-5	30.00	0.0005	
		Surface	0.001	Potassium hydroxide	1310-58-3	100.00	0.0016	0.002
			0.019	Sodium Hypophosphite Monohydrate	10039-56-2	100.00	0.031	0.031
12	Solder Preform x2	Solder	0.052	Tin	7440-31-5	96.50	0.081	0.084
				Silver	7440-22-4	3.50	0.003	
13	Adhesive	Silicone	0.8	Limestone	1317-65-3	90.00	1.166	1.296
				Trimethoxyvinylsilane	2768-02-7	5.00	0.065	
				3-(Trimethoxysilyl) Propylamine	13822-56-5	4.00	0.052	
				Quartz (SiO2)	14808-60-7	1.00	0.013	
14	Conformal coating	Coating Silica	0.7000	Dichlorodimethyl	68611-44-9	97.00	1.100	1.134
				Aminopropyltriethoxysilane	919-30-2	3.00	0.034	
15	Screw	Stainless Steel 304	0.257	Carbon	7440-44-0	0.08	0.0003	0.415
				Manganese	7439-96-5	2.00	0.008	
				Phosphorus	7723-14-0	0.05	0.0002	
				Sulfur	7704-34-9	0.03	0.0001	
				Silicon	7440-21-3	0.75	0.003	
				Chromium	7440-47-3	18.00	0.075	
				Nickel	7440-02-0	8.00	0.033	
				Iron	7439-89-6	71.10	0.295	
16	Top Housing	Resin	6.100	Polyphenylene Sulfide	26125-40-6	59.50	5.879	9.881
				Glass Fiber	65997-17-3	40.00	3.952	
				Carbon Black	1333-86-4	0.50	0.049	
17	Bottom Housing	Resin	5.245	Polyphenylene Sulfide	26125-40-6	59.50	5.055	8.496
				Glass Fiber	65997-17-3	40.00	3.398	
				Carbon Black	1333-86-4	0.50	0.042	
18	Shunt	Manganin	3.660	Copper	7440-50-8	86.00	5.099	5.929
				Manganese	7439-96-5	12.00	0.711	
				Nickel	7440-02-0	2.00	0.119	
		Plating	0.005	Nickel	7440-02-0	100.00	0.008	0.008

		Copper Alloy	36.503	Copper	7440-50-8	99.95	59.100	59.130
				Oxygen	7782-44-7	0.05	0.030	
19	Silicone	Part A	0.770	Dimethyl Silicone Resin	63148-62-9	44.03	0.549	1.247
				3-Aminopropyltrimethoxysilane	13822-56-5	5.25	0.065	
				Hexamethyldisiloxane	107-46-0	2.40	0.030	
				Quartz	14808-60-7	35.03	0.437	
				Silicon Dioxide	7631-86-9	13.29	0.166	
20	Silicone	Part B	0.770	Dimethyl Silicone Resin	63148-62-9	47.50	0.592	1.247
				Quartz	14808-60-7	35.60	0.444	
				Silicon Dioxide	7631-86-9	16.90	0.211	
21	Solder Paste	Solder	0.003	Tin	7440-31-5	93.50	0.0045	0.005
				Silver	7440-22-4	5.50	0.0003	
				Misc, not to declare	Proprietary	1.00	0.00005	
22	Solder Wire P/N: 17790-15301	Lead Free Solder	0.020	Tin	7440-31-5	88.00	0.029	0.032
				Silver	7440-22-4	7.00	0.002	
				Copper	7440-50-8	5.00	0.0016	
		Total Weight	**61.73**					

This Document was updated on: 02/18/2026

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
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